

AULB3034-VB Datasheet

N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY

| | |
|--|---------|
| V_{DS} (V) | 40 |
| $R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V | 0.00084 |
| I_D (A) | 409 |
| Configuration | Single |
| Qg (nC) | 250 |

FEATURES

- Trench Power MOSFET
- 100 % R_g and UIS Tested

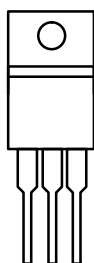
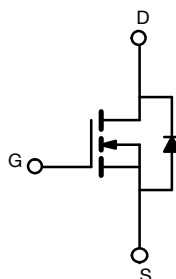
APPLICATIONS

- Synchronous Rectification
- Power Supplies



RoHS
COMPLIANT
HALOGEN
FREE

TO-220AB

G D S
Top View

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise noted)

| PARAMETER | SYMBOL | LIMIT | UNIT |
|---|----------------|---------------------------|------------------|
| Drain-source voltage | V_{DS} | 40 | V |
| Gate-source voltage | V_{GS} | ± 20 | |
| Continuous drain current ^a | I_D | $T_C = 25^\circ\text{C}$ | A |
| | | $T_C = 125^\circ\text{C}$ | |
| Continuous source current (diode conduction) ^a | I_S | 409 | |
| Pulsed drain current ^b | I_{DM} | 600 | |
| Single pulse avalanche current | I_{AS} | 100 | mJ |
| Single pulse avalanche energy | | | |
| Maximum power dissipation ^b | P_D | $T_C = 25^\circ\text{C}$ | W |
| | | $T_C = 125^\circ\text{C}$ | |
| Operating junction and storage temperature range | T_J, T_{stg} | -55 to +175 | $^\circ\text{C}$ |

THERMAL RESISTANCE RATINGS

| PARAMETER | SYMBOL | LIMIT | UNIT |
|--------------------------|------------|-------|--------------------|
| Junction-to-ambient | R_{thJA} | 40 | $^\circ\text{C/W}$ |
| Junction-to-case (drain) | R_{thJC} | 0.4 | |

Notes

a. Based on $T_J = 25^\circ\text{C}$.

b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$

c. When mounted on 1" square PCB (FR4 material)

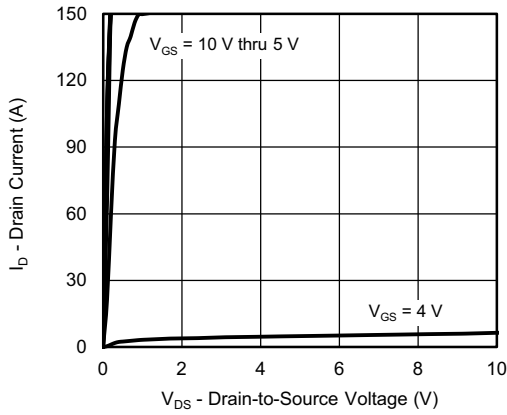
| SPECIFICATIONS (T _C = 25 °C, unless otherwise noted) | | | | | | | |
|---|----------------------|---|---|------|---------|--------|------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | | 40 | - | - | V |
| Gate-source threshold voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | | 2.5 | 3.0 | 3.5 | |
| Gate-source leakage | I _{GSS} | V _{DS} = 0 V, V _{GS} = ± 20 V | | - | - | ± 100 | nA |
| Zero gate voltage drain current | I _{DSS} | V _{GS} = 0 V | V _{DS} = 40 V | - | - | 1 | μA |
| | | V _{GS} = 0 V | V _{DS} = 40 V, T _J = 125 °C | - | - | 50 | |
| | | V _{GS} = 0 V | V _{DS} = 40 V, T _J = 175 °C | - | - | 300 | μA |
| On-state drain current ^a | I _{D(on)} | V _{GS} = 10 V | V _{DS} ≥ 5 V | 100 | - | - | A |
| Drain-source on-state resistance ^a | R _{DS(on)} | V _{GS} = 10 V | I _D = 35 A | - | 0.00084 | - | Ω |
| | | V _{GS} = 10 V | I _D = 35 A, T _J = 125 °C | - | 0.00140 | - | |
| | | V _{GS} = 10 V | I _D = 35 A, T _J = 175 °C | - | 0.00164 | - | |
| Forward transconductance ^b | g _{fs} | V _{DS} = 15 V, I _D = 30 A | | - | 196 | - | S |
| Dynamic ^b | | | | | | | |
| Input capacitance | C _{iss} | V _{GS} = 0 V | V _{DS} = 25 V, f = 1 MHz | - | 11 938 | 15 525 | pF |
| Output capacitance | C _{oss} | | | - | 11 163 | 14 520 | |
| Reverse transfer capacitance | C _{rss} | | | - | 282 | 370 | |
| Total gate charge ^c | Q _g | V _{GS} = 10 V | V _{DS} = 20 V, I _D = 100 A | - | 158 | 250 | nC |
| Gate-source charge ^c | Q _{gs} | | | - | 44 | - | |
| Gate-drain charge ^c | Q _{gd} | | | - | 22 | - | |
| Gate resistance | R _g | f = 1 MHz | | 2.70 | 5.44 | 8.20 | Ω |
| Turn-on delay time ^c | t _{d(on)} | V _{DD} = 20 V, R _L = 0.2 Ω I _D ≅ 100 A, V _{GEN} = 10 V, R _g = 1 Ω | | - | 16 | 25 | ns |
| Rise time ^c | t _r | | | - | 10 | 17 | |
| Turn-off delay time ^c | t _{d(off)} | | | - | 103 | 160 | |
| Fall time ^c | t _f | | | - | 61 | 95 | |
| Source-Drain Diode Ratings and Characteristics ^b | | | | | | | |
| Pulsed current ^a | I _{SM} | | | - | - | 260 | A |
| Forward voltage | V _{SD} | I _F = 60 A, V _{GS} = 0 V | | - | 0.81 | 1.5 | V |
| Body diode reverse recovery time | t _{rr} | I _F = 30 A, di/dt = 100 A/μs | | - | 165 | 350 | ns |
| Body diode reverse recovery charge | Q _{rr} | | | - | 530 | 1100 | nC |
| Reverse recovery fall time | t _a | | | - | 66 | - | ns |
| Reverse recovery rise time | t _b | | | - | 99 | - | |
| Body diode peak reverse recovery current | I _{RM(REC)} | | | - | -6.2 | - | A |

Notes

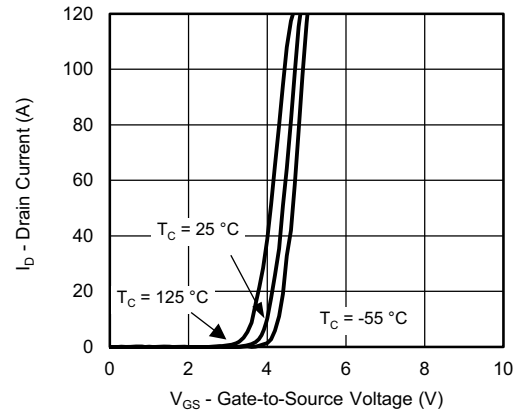
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
 b. Guaranteed by design, not subject to production testing
 c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

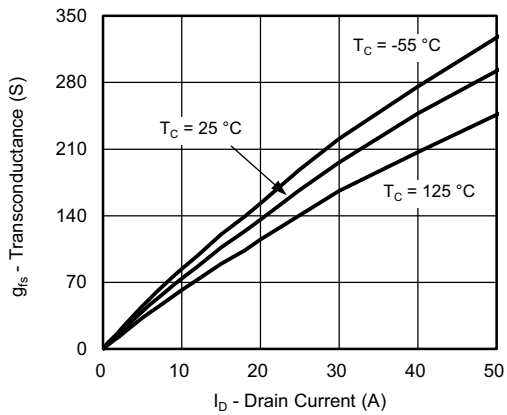
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)



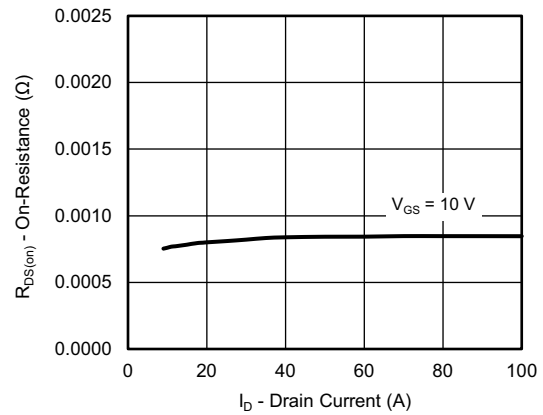
Output Characteristics



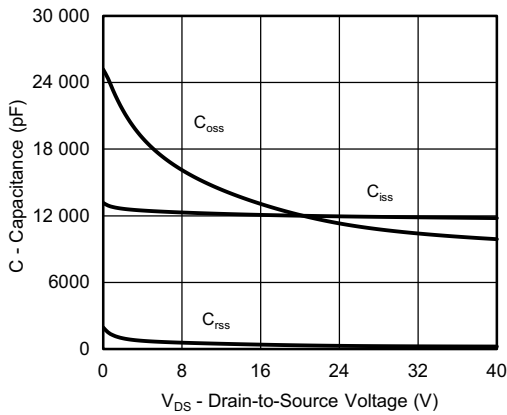
Transfer Characteristics



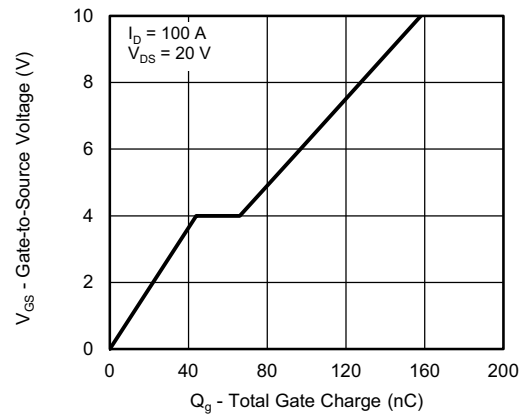
Transconductance



On-Resistance vs. Drain Current

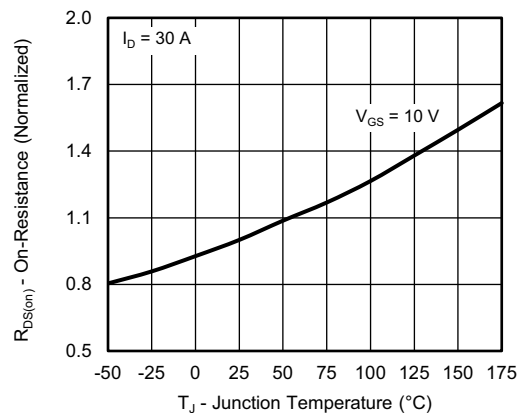


Capacitance

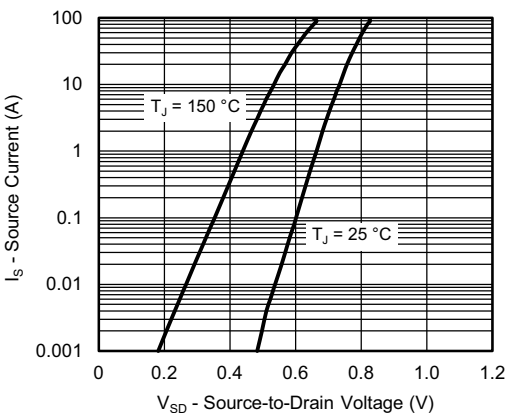


Gate Charge

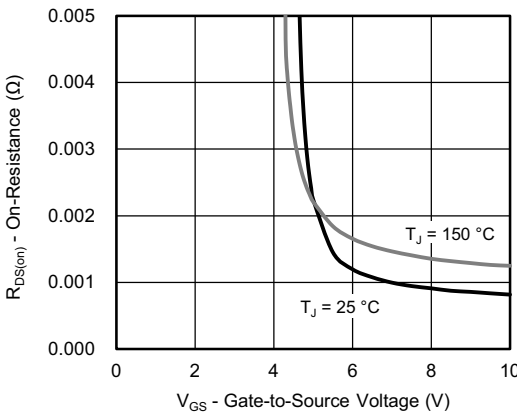
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)



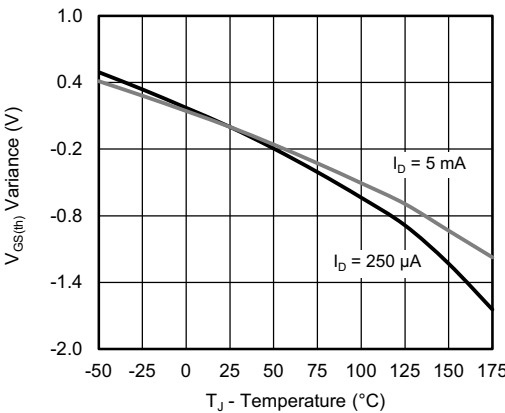
On-Resistance vs. Junction Temperature



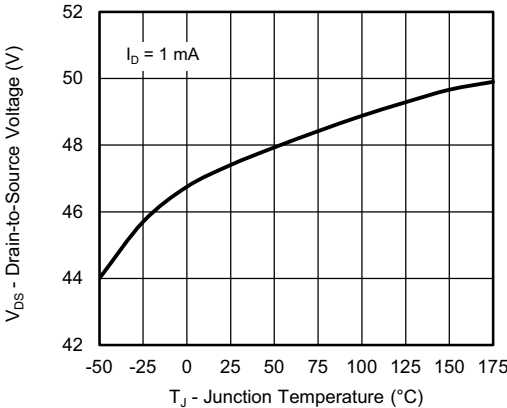
Source Drain Diode Forward Voltage



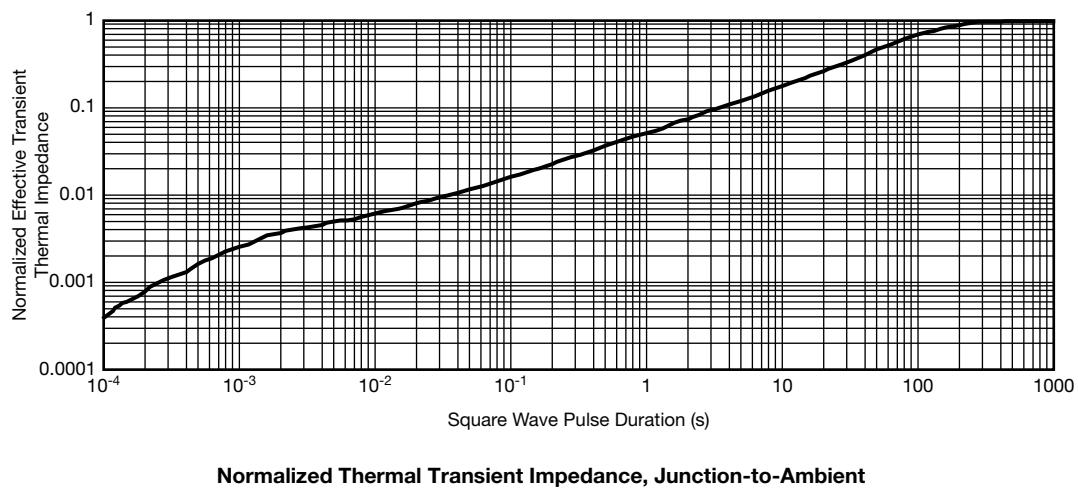
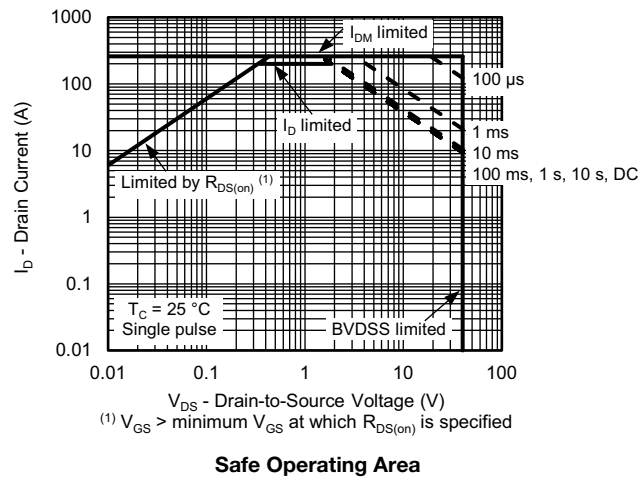
On-Resistance vs. Gate-to-Source Voltage

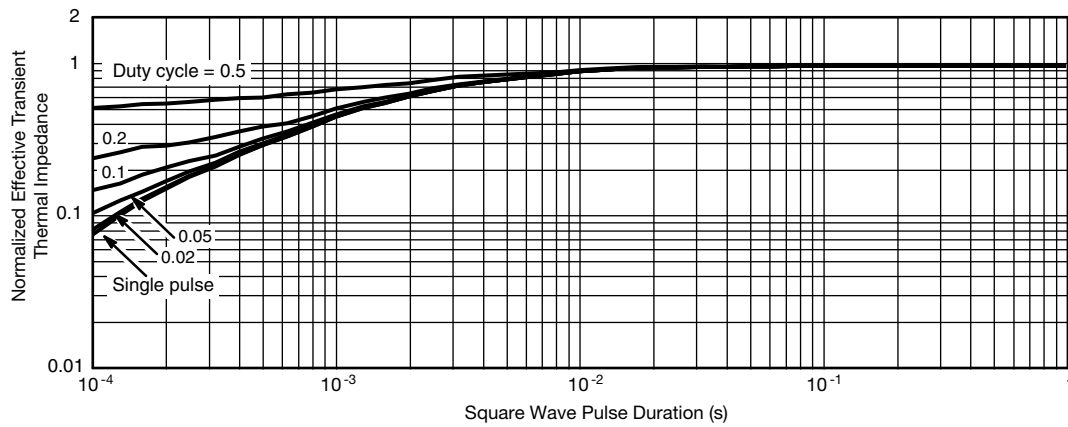


Threshold Voltage



Drain Source Breakdown vs. Junction Temperature

THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)


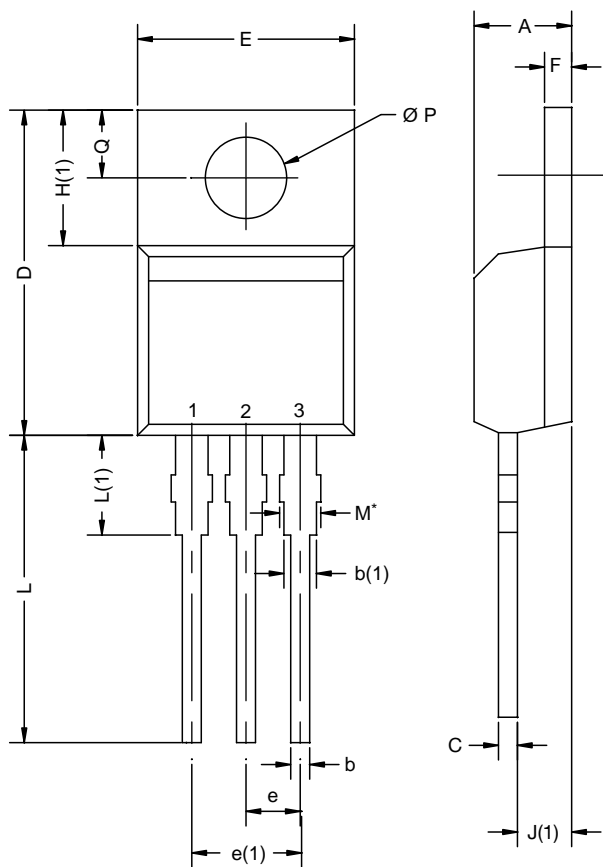
THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)


Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^{\circ}\text{C}$)
 are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

TO-220AB



| DIM. | MILLIMETERS | | INCHES | |
|-----------------|-------------|-------|--------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.25 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.01 | 0.027 | 0.040 |
| b(1) | 1.20 | 1.73 | 0.047 | 0.068 |
| c | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.85 | 15.49 | 0.585 | 0.610 |
| E | 10.04 | 10.51 | 0.395 | 0.414 |
| e | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.09 | 6.48 | 0.240 | 0.255 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.35 | 14.02 | 0.526 | 0.552 |
| L(1) | 3.32 | 3.82 | 0.131 | 0.150 |
| $\varnothing P$ | 3.54 | 3.94 | 0.139 | 0.155 |
| Q | 2.60 | 3.00 | 0.102 | 0.118 |

ECN: X12-0208-Rev. N, 08-Oct-12
DWG: 5471

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM

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